L Numbe	r Hite	S   Search Text	155	
-	412		DB	Time stamp
	1	(110//201/.0010.	USPAT;	2002/05/10 13:06
-	240	(156/345.48).CCLS.	US-PGPUB USPAT;	2002/05/07 12 55
1			US-PGPUB	2002/05/07 18:12
-	117	(118/723an).CCLS.	USPAT;	2002/05/07 19:10
			US-PGPUB	2002/05/07 18:12
-	136	118/723i.ccls. and 156/345.48.ccls.	USPAT;	2002/05/08 11:30
			EPO; JPO	2002/03/08 11:30
-	41	(118/723i.ccls. or 156/345.48.ccls. or	USPAT;	2002/05/08 11:31
		118/723an.ccls.) and ((Faraday adj	EPO; JPO	2002/05/00 11:51
		shield))	1	
-	10	("4659449"   "5105761"   "5134965"	USPAT	2002/05/08 11:50
ļ		"5290993"   "5401350"   "5415728"		1112, 00, 00 111.00
		"5522934"   "5614055"   "5753044"		
1_	5	"5777289").PN.		
}	) 3		USPAT	2002/05/08 11:52
_	192	"5753044"   "5777289").PN.		
	192	1 (===, -================================	USPAT;	2002/05/08 11:57
		118/723an.ccls.) and (shield (Faraday adj shield))	EPO; JPO	
-	59310			
		Hears (chamber reactor)	USPAT;	2002/05/08 13:21
-	1	((resist\$3 adj heat\$3) near5 (chamber	EPO; JPO	2000/05/22 22
1	1	reactor)) and ((118/723i.ccls. or	USPAT;	2002/05/08 13:23
		156/345.48.ccls. or 118/723an.ccls.) and	EPO; JPO	
		(shield (Faraday adj shield)))		
-	384	(resist\$3 adj heat\$3) near5 (chamber	USPAT;	2002/05/08 14:31
		reactor)	EPO; JPO	2002/03/08 14:31
-	125		USPAT;	2002/05/08 13:29
		reactor) and (vapor adj deposition)	EPO; JPO	2002/03/08 13:29
-	259	((resist\$3 adj heat\$3) near5 (chamber	USPAT;	2002/05/08 14:05
		reactor)) not ((resist\$3 adj heat\$3) near5	EPO; JPO	2002,00,00 14.05
		(chamber reactor) and (vapor adj		
_	1.0	deposition))		
	12		USPAT	2002/05/08 14:22
	165	(heat\$3 adj wire) near5 (chamber reactor)	USPAT;	2002/05/08 14:33
1_	164	//hoat62 add adams	EPO; JPO	1
	104		USPAT;	2002/05/08 16:03
		reactor)) not ((resist\$3 adj heat\$3) near5 (chamber reactor))	EPO; JPO	
-	1440			
]		110,721.0013.	USPAT;	2002/05/08 16:21
-	30	118/724.ccls. and (heat\$3 adj wire)	EPO; JPO USPAT;	2002/05/00 00 10
		(modet of add wile)	EPO; JPO	2002/05/09 08:49
-	12	4958592.URPN.	USPAT	2002/05/08 16:17
-	20	118/724.ccls. and 118/723i.ccls.	USPAT;	2002/05/08 16:17
			EPO; JPO	2002/03/08 18:49
-	6	("5001113"   "5365057"   "5401350"	USPAT	2002/05/08 16:37
		"5556501"   "5614055"   "5865896") PN		-552,55,55 10.57
-	1085	c23c016/48.ipc.	EPO; JPO	2002/05/08 16:56
-	4	c23c016/48.ipc. and ((heat\$3 adj wire)	EPO; JPO	2002/05/08 16:51
1_	,,	(resistive adj heat) (resist\$ adj heat))		
1	15	c23c016/48.ipc. and "applied	EPO; JPO	2002/05/08 16:57
_		materials".as.		
_	317	5690050.URPN.	USPAT	2002/05/08 17:17
	31/	118/724.ccls. and (((heat\$3 adj	USPAT;	2002/05/09 10:09
		element)(resist\$3 adj heat\$3) heat) near5 (chamber reactor))	EPO; JPO	
-	109	156/345.37.ccls.		
	100	100/040.07.0013.	USPAT;	2002/05/09 10:24
_	114	156/345.37.ccls.	EPO; JPO	2000 (05 (05
			USPAT;	2002/05/09 14:22
			US-PGPUB;	
-	1963	118/725.ccls.	EPO; JPO USPAT;	2002/05/02 14 25
		1	US-PGPUB;	2002/05/09 14:23
			EPO; JPO	
-	23	118/725.ccls. and ((resist\$3 adj heat)	USPAT;	2002/05/09 14:26
	l	(heat\$3 adj wire) near5 (substrate	US-PGPUB;	2002/03/03 14:20
		workpiece wafer))	EPO; JPO	

1187725.ccls. and (((resist33 adj heat) (whet33 adj wire)) near(substrate workplece wafer)   11				_	
	-		6 118/725.ccls. and (((resist\$3 adj heat)	USPAT;	2002/05/09 14:30
-   339   (((resist3 ad j heat) (heat3 ad j wire)   near5(substrate workpiece wafer)   0S-PGUB;   Part   0S-PAT;   0S-PGUB;   Part   0S-PGUB;   Part   0S-PGUB;   Part   0S-PAT;   0S-PGUB;   Part   0S-PGUB;   Part   0S-PAT;   0S-PAT;   0S-PGUB;   0S-PAT;   0S-PGUB;   0S-PAT;   0			(heat\$3 adj wire)) near5(substrate	US-PGPUB;	
		30.	workpiece wafer))	EPO; JPO	
	-	38	(((resist\$3 adj heat) (heat\$3 adj wire))		2002/05/09 16:28
Comparison of the comparison	İ		near5(substrate workpiece wafer))	US-PGPUB;	
Compared to the control of the con	1_		()-011001 (0 )	EPO; JPO	
Rear's (substrate workpiece wafer)   11   12   12   12   12   12   13   12   12		1 '	(nullu21/\$.1pc. and c23c016/\$.ipc.) and	USPAT;	2002/05/09 14:41
C220c16/8.ipc. and (((resist\$3 adj heat) (heat\$3 adj wire)) near5(substrate workpiece wafer))			(((resist\$3 adj heat) (heat\$3 adj wire))	US-PGPUB;	
(heat33 adj wire)) near5(substrate   Us-PGFUB; pro; JPO (substrate) (hol1021/5.jpc.) and (((resist\$3 adj heat)) (hol1021/5.jpc.) and (((substrate)) (hol	I _	1 .	nears(substrate workpiece wafer))	EPO; JPO	
	1	1	((resist\$3 adj heat)		2002/05/09 14:43
1	j		(neat) adj wire)) near5(substrate		
Cheat33 adj wire)   near5(substrate workpiece wafer)	_	5	workpiece water))	EPO; JPO	İ
Total		1	(heats) add wire) result (resists) add heat)		2002/05/09 14:55
T941   (substrate workpiece wafer) adj conductive   USPAT; USPAT; USPAC; USPAT; USPAC; USPAT; USPAC; USPA			Workniece wafor!		
Conductive   Con	_	7941	(Substrate workpiece wafer) add and well	EPO; JPO	
26835   (substrate workpiece wafer) near conductive   C	1		(substract workprece water) adj conductive		2002/05/09 16:30
2002/05/09 16:29					
Conductive	-	26835	(substrate workniege wafer) noar		
- 85726 vapor adj deposition	1			1	2002/05/09 16:29
Solution   Solution					
- 3206 (vapor adj deposition) and ((substrate workpiece wafer) near conductive)  - 2 156/345.48 and ((substrate workpiece wafer) adj conductive)  - 3 156/345.48 and ((substrate workpiece wafer) near conductive)  - 4 156/345.48 and ((substrate workpiece wafer) near conductive)  - 5 156/345.48 and ((substrate workpiece wafer) near conductive)  - 6 1 156/345.48 and ((substrate workpiece wafer) near conductive)  - 7 (("5690050") or ("5944899") or ("5735993") or ("5922233") or ("6077384")).PN.  - 8 (("5522233") or ("6077384")).PN.  - 1211 ((156/345.37) or (156/345.48) or (118/7231) or (11	_	85726	vapor adi deposition		2002/25/22
Same   Canaday adj shield   Sepo; JPO			1	i i	2002/05/09 16:30
Compared deposition and ((substrate workpiece wafer) near conductive)					
workpiece wafer) near conductive	-	3206			2002/05/00 35 55
2   156/345.48 and ((substrate workpiece wafer) adj conductive)   2002/05/09 16:31   20		1			2002/05/09 16:30
2   156/345.48 and ((substrate workpiece wafer) adj conductive)   USPAT; EPO; JPO USPAT; US-PGPUB; SPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; EPO; JPO USPAT; EPO; JPO USPAT; US-PGPUB USPAT; EPO; JPO USPAT; US-PGPUB USPAT; EPO; JPO USPAT; EPO; JPO USPAT; US-PGPUB USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; US-PGPUB USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; US-PGPUB USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO USPAT; EPO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; J		1			
Wafer   adj conductive   US-PGPUB;   PO; JPO   USPAT;   US-PGPUB   USPAT;   US-PGPUB;   USPAT;	-	2	156/345.48 and ((substrate workpiece	· ·	2002/05/00 16 21
156/345.48 and ((substrate workpiece wafer) near conductive)	i		wafer) adj conductive)	•	2002/05/09 16:31
SPAT;   SPAT					
Wafer)   near conductive)	_	9	156/345.48 and ((substrate workpiece		2002/05/00 16.31
To (("5690050") or ("5944899") or ("5735993") or ("6177646") or ("6095083") or ("5922223") or ("6077384")).PN.  314 (219/121.43).CCLS.  1211 ((156/345.37) or (156/345.48) or (118/7231) or (118/723an) or (118/7231) or (1			wafer) near conductive)		2002/03/09 16:31
C(*559005*) or (*5734899*) or (*5735993*) or (*5735993*) or (*6177646*) or (*6077384*)).PN.   USPAT; US-PGPUB   USPAT; USPAT; USPAT; EPO; JPO   USPAT; EPO; JPO   USPAT; EPO; JPO   USPAT;					
Or ("6177646") or ("6095083") or ("5092223") or ("6077384")).PN.	-	7	(("5690050") or ("5944899") or ("5735993")		2002/05/10 13:17
1314 (219/121.43).CCLS.			or ("6177646") or ("6095083") or		2002/03/10 13:1/
1211   ((156/345.37) or (156/345.48) or (118/723i) or (118/723an) or (118/723i) or (118/723an) or (118/723i)  or (118/723ii) or (118/723ii) or (118/723ii) or (118/723ii) or (118/723ii) or (118/723			("5922223") or ("6077384")).PN.		
1211	_	314	(219/121.43).CCLS.	USPAT;	2002/05/10 13:18
(118/723i) or (118/723an) or (118/		1011			-102, 00, 10 13.10
118/723r) or (118/723an) or (118/723r) or (118/723r) or (118/723r) or (118/723r) or (118/723an) or (118/723an) or (118/723an) or (118/723r) or (118/723an) or (118/723r) or (118/723an) or (118/723r)	-	1211		USPAT;	2003/01/16 13:56
128		1	(118/723i) or (118/723an) or	EPO; JPO	
(118/723i) or (118/723an) or (118/723i) or (118/723an) or (118/723i) or (118/723i) or (118/723an) or (128/72i) por (118/723i) or (118/723an) or (128/72i) por (118/723i) or (128/72ii) por (118/723i) or (128/72iii) por (128/72iii) por (128/72iii) por (128/72iiii) por (128/72iiii) por (128/72iiii) por (128/72iiii) por (128/72iiii) por (128/72iii) por (128/7	-	120	(118//23r)).CCLS.		
Clis/7231) or (187/23an) or (187/23an) or (118/723an) or (128/72; and (1297) JPO; betwent (1297) JPO; be		128	(((156/345.37) or (156/345.48) or		2003/01/16 14:32
-		1	(118/7231) or (118/723an) or	EPO; JPO	İ
P8 heat\$3 same (faraday adj shield)    Po	_	72	(118/723r)).CCLS.) not @pd<=20020508		
Second   S		/3	neacşs same (faraday adj shield)	USPAT;	2003/01/16 14:33
EPO; JPO; DERWENT USPAT 2003/01/16 14:36    "5540800"   "5650032"   "5681418"   USPAT 2003/01/16 14:36   USPAT 2003/01/16 14:36   USPAT 2003/01/16 14:37   USPAT 2003/01/16 14:37   USPAT 2003/01/16 16:12   USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;	_	98	heat\$3 came (formation and all all)		
B			neacys same (laraday adj shield)		2003/01/16 16:11
S		1			
"5944899"   "6280563").PN. ("5540800"   "5650032"   "5681418"   USPAT 2003/01/16 14:37  "5944899"   "6280563").PN.  "5944899"   "6280563").PN.  USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;	_	8	("5540800"   "5650032"   "5691410"		
- 8		1	"5685941"   "5811022"   "5003106"	USPAT	2003/01/16 14:36
S   ("5540800"   "5650032"   "5681418"   USPAT   2003/01/16 14:37   "5685941"   "5811022"   "5903106"   USPAT   2003/01/16 14:37   USPAT; EPO; JPO; DERWENT USPAT; EPO; J		1	"5944899"   "6280563"\ DNI	ł	
- 0	-	8	("5540800"   "5650032"   "5691410"	HCDAG	0000 /00 /0
- 0   "5944899"   "6280563").PN.   W000/52973			"5685941"   "5811022"   "5903106"	USPAT	2003/01/16 14:37
USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;			"5944899"   "6280563") PN		
- 0 00/52973	-	0	WO00/52973	IIGDAT.	2002/01/16 15 15
DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;					2003/01/16 16:12
USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;					
- 43 "52973"  "52973"  135 holland-john\$.in.  6 li-maocheng\$.in.    CSPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;	-	0	00/52973		2003/01/16 16 16
DERWENT USPAT; 2003/01/16 16:23 EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;				·	2003/01/16 16:12
- 43 "52973"  - 135 holland-john\$.in.  - 6 li-maocheng\$.in.  USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO;					
- 135 holland-john\$.in.	_	43	"52973"		2003/01/16 16:22
DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; EPO; JPO;					-505/01/10 10:23
135 holland-john\$.in. USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT; EPO; JPO; EPO; JPO; DEPO; JPO; EPO; JPO; EPO; JPO;					İ
EPO; JPO; DERWENT USPAT; EPO; JPO; EPO; JPO;	-	135	holland-john\$.in.	_	2003/01/16 16:24
6 li-maocheng\$.in. DERWENT USPAT; EPO; JPO; 2003/01/16 16:25					
6   li-maocheng\$.in.					
EPO; JPO;	-	6	li-maocheng\$.in.		2003/01/16 16:25
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-	9	todorov-valentin\$.in.	USPAT;	2003/01/16 16:29
	1		EPO; JPO;	2003/01/16 16:29
-	6	leahey-patrick\$.in.	DERWENT	
	8		USPAT;	2003/01/16 16:31
		3	EPO; JPO;	
-	7	hartlage-robert\$.in.	DERWENT	2222 (22 (2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
			USPAT; EPO; JPO;	2003/01/16 16:35
_	1	nguyen-hoan\$.in.	DERWENT	
	58		USPAT;	2003/01/16 16:37
			EPO; JPO;	
_	7657	"applied materials".as.	DERWENT	
			USPAT;	2003/01/16 16:37
			EPO; JPO;	
-	10	holland-john\$.in. and "applied	DERWENT USPAT;	2002/01/16 15 07
		materials".as.	EPO; JPO;	2003/01/16 16:37
			DERWENT	

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